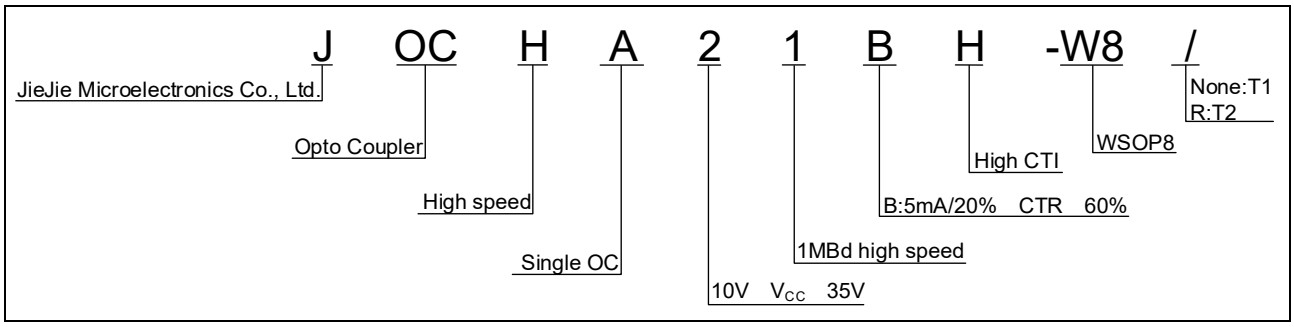
	Output Current	I_O	8	mA
	Output Power Dissipation	P_O	100	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	7500	Vrms
Operating Temperature		T_{opr}	-55~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

100μs pulse, 100Hz frequency
AC for 1minute, R.H.=40~60%

			V_{CC}=5V				
	Common Mode Transient Immunity at Logic High	CM_H	I_F=0mA, V_{CM}=400Vpp, R_L=4.1kΩ	15	20	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM_L	I_F=16mA, V_{CM}=400Vpp, R_L=4.1kΩ	-15	-20	-	kV/μs



None/R	1200 Units/Reel

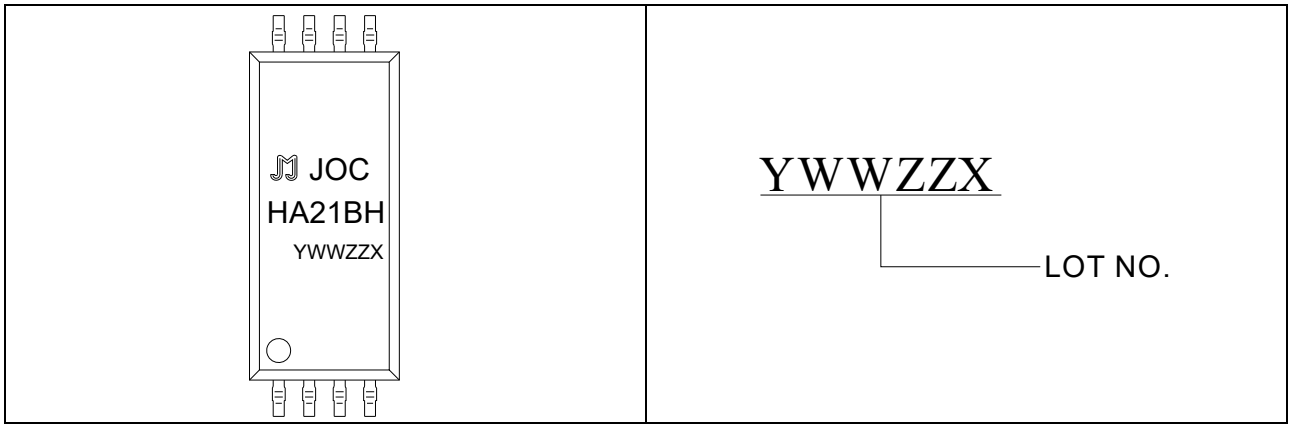


FIG.1: Forward Current vs. Forward Voltage

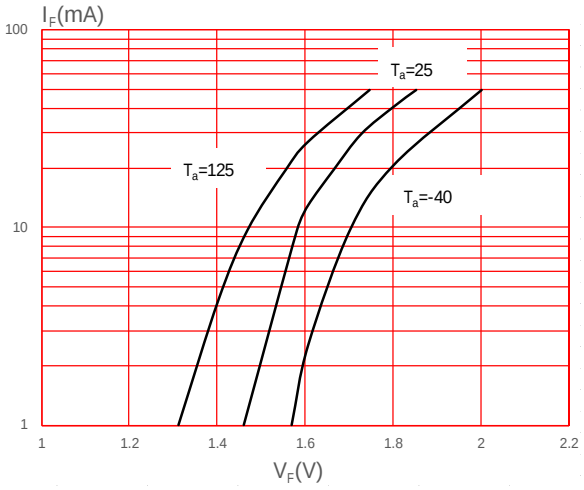


FIG.2: High Level Output Current vs. Ambient Temperature

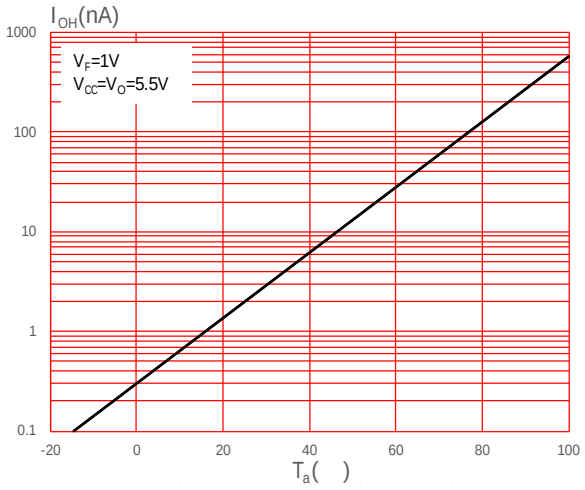


FIG.3: Output Current vs. Forward Current

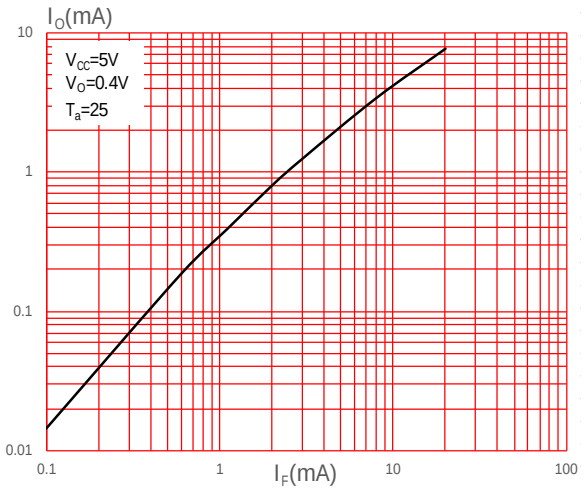


FIG.4: Current Transfer Ratio vs. Forward Current

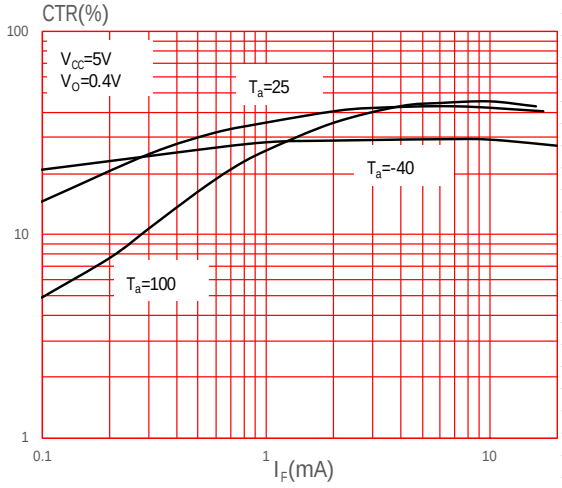


FIG.5: Normalized Current Transfer Ratio vs. Ambient Temperature

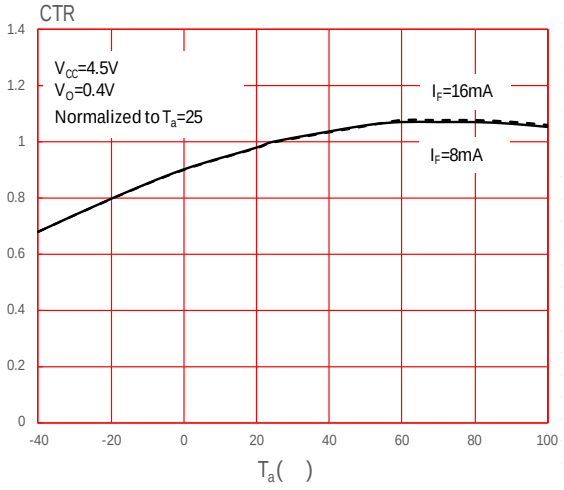


FIG.6: Output Current vs. Output Voltage

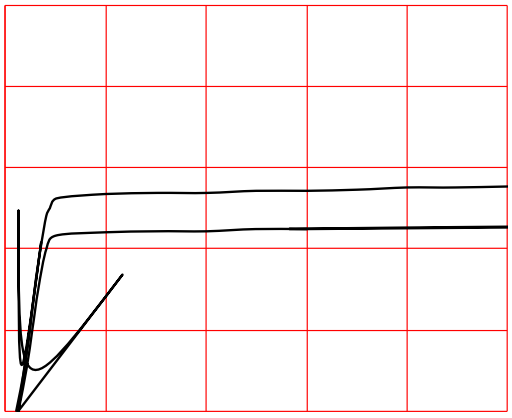


FIG.7: Low Level Output Voltage vs. Ambient Temperature

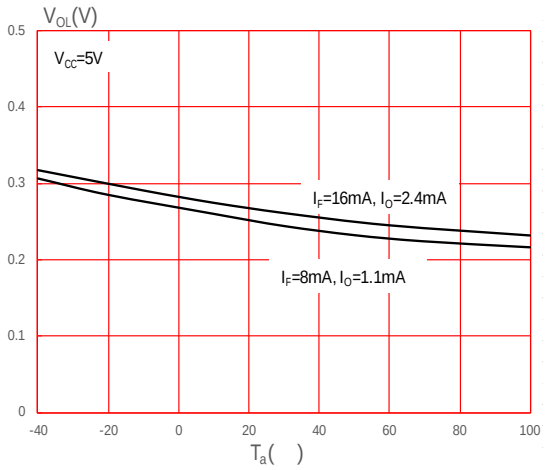


FIG.8: Propagation Delay vs. Load Resistance

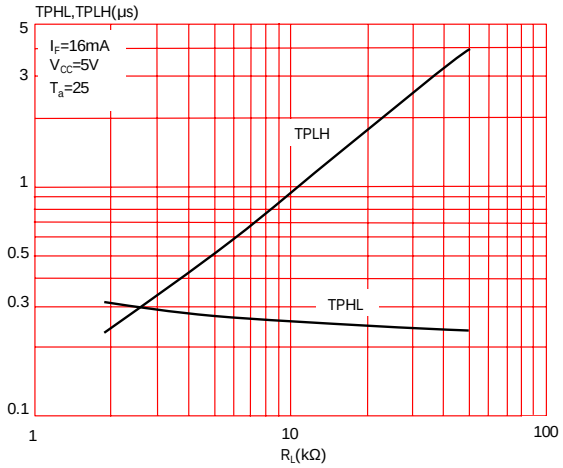


FIG.9: Propagation Delay vs. Ambient Temperature

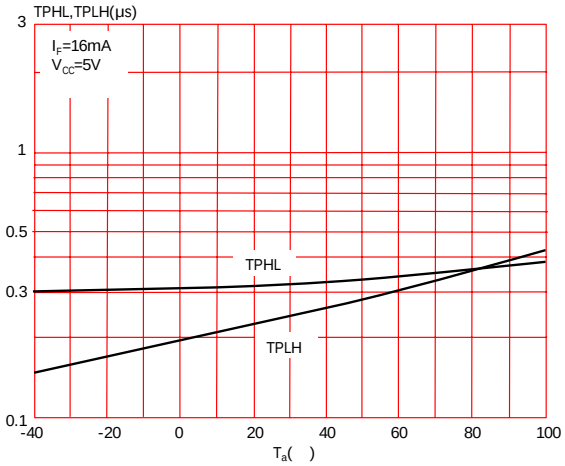


Fig.10: Test Circuit of tPHL, tPLH

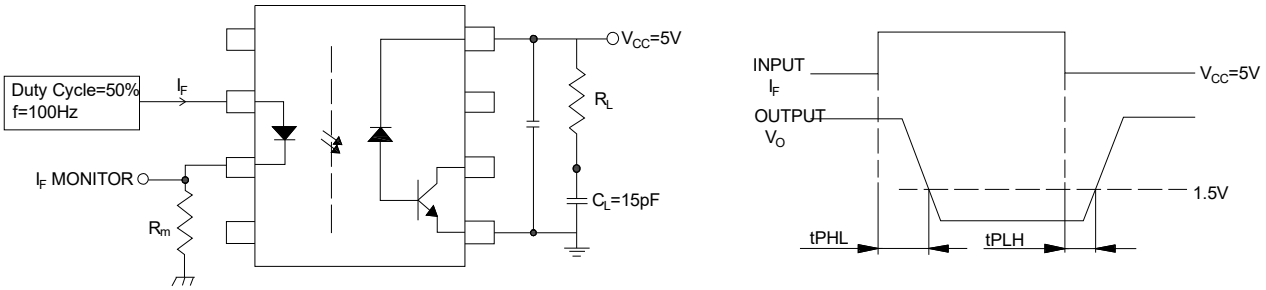
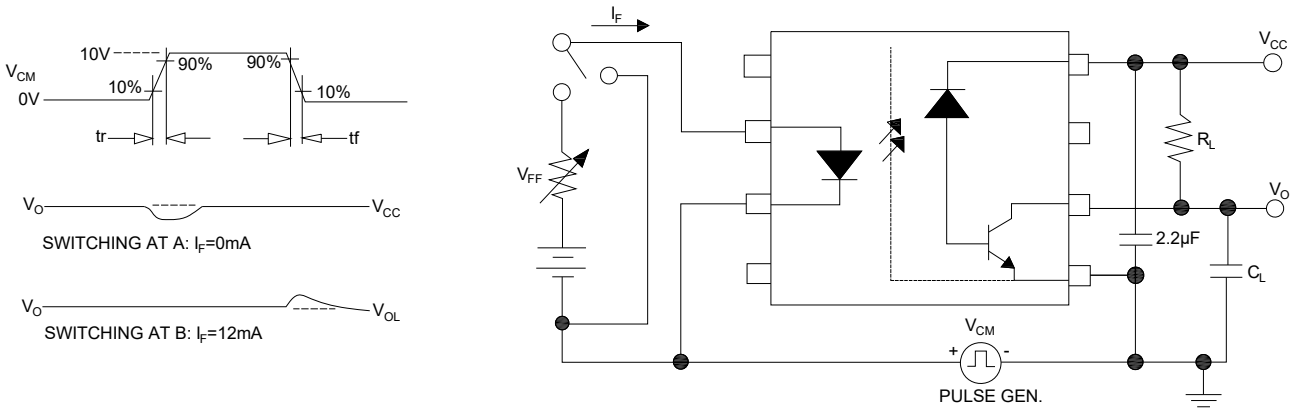
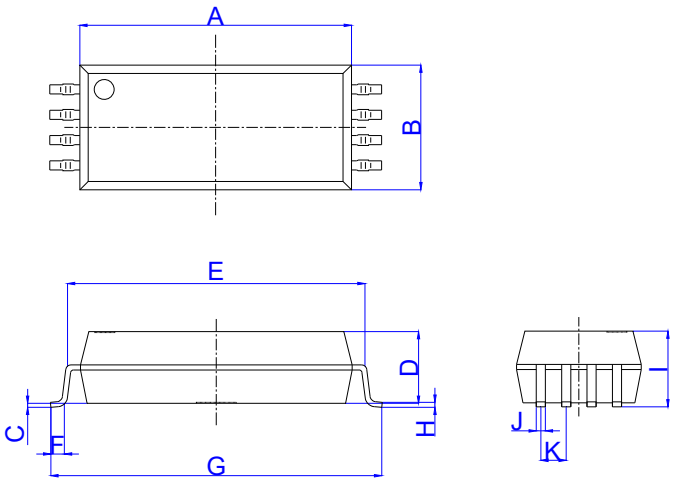
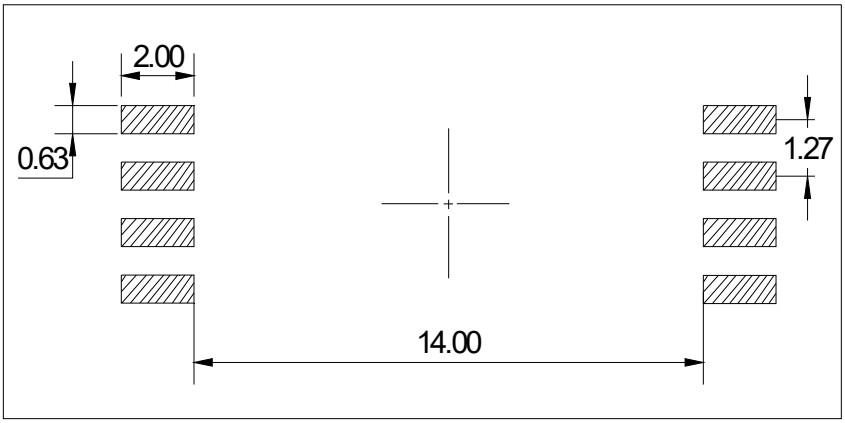


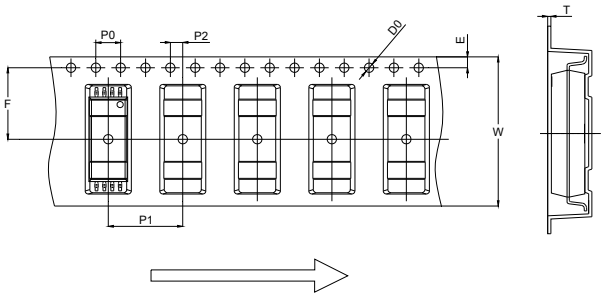
Fig.11: Test Circuit for Transient Immunity and Typical Waveforms



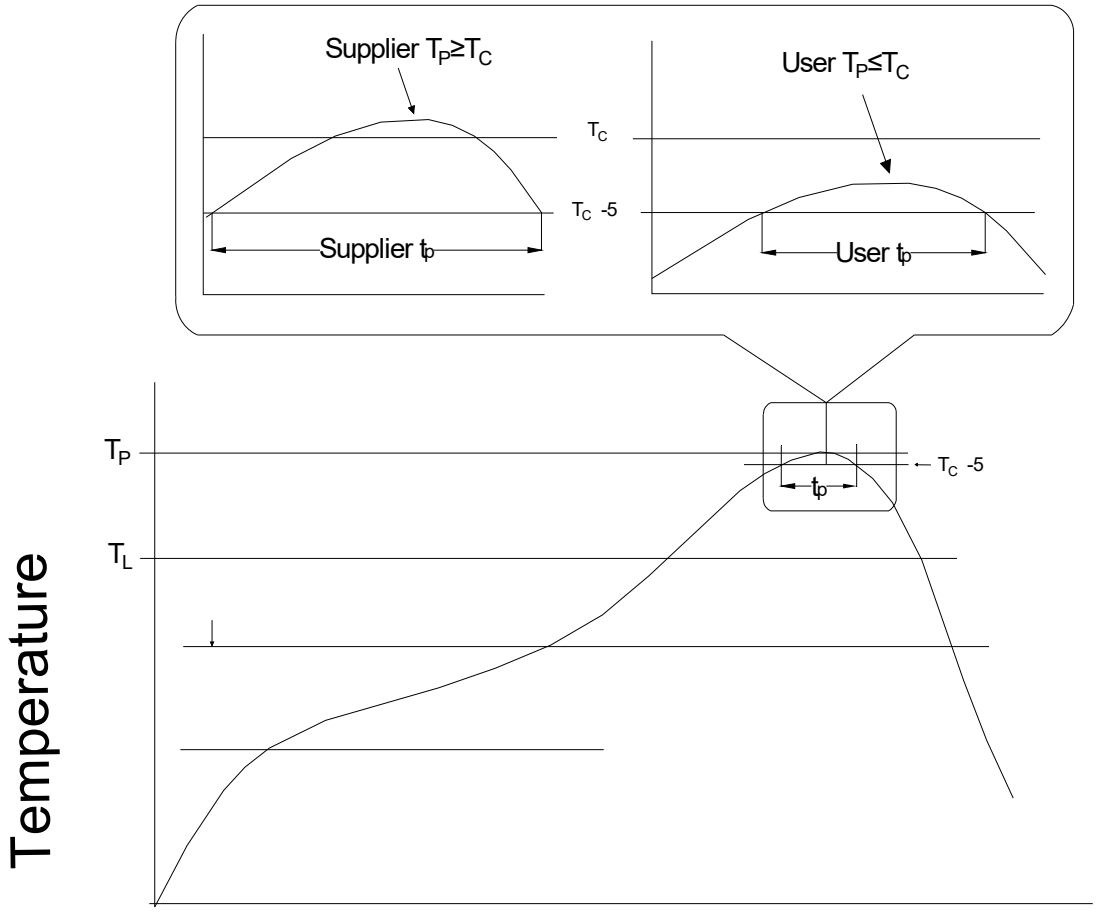


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	13.50		13.70	0.531		0.539
B	6.15		6.35	0.242		0.250
C	0.10		0.30	0.004		0.012
D	3.50		3.70	0.138		0.146
E	14.71		15.31	0.579		0.603
F	0.52		1.02	0.020		0.040
G	16.36		16.86	0.644		0.664
H	0.10		0.40	0.004		0.016
I	3.65		3.95	0.144		0.156
J	0.307		0.607	0.012		0.024
K	1.02		1.52	0.040		0.060





Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	11.40	11.50	11.60	0.449	0.453	0.457
T	0.35	0.40	0.45	0.014	0.016	0.018
W	23.70	24.00	24.30	0.933	0.945	0.957


Supplier $T_P \geq T_C$
User $T_P \leq T_C$
T_C
T_C -5
Supplier t_p
User t_p
T_P
T_L
T_C -5
t_p
Temperature

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1